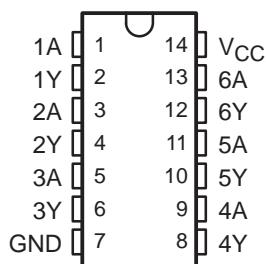
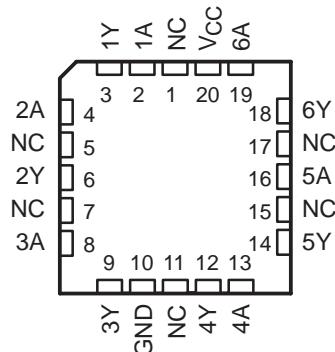


- 4.5-V to 5.5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 8.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible

**SN54ACT04 . . . J OR W PACKAGE  
SN74ACT04 . . . D, DB, N, NS, OR PW PACKAGE  
(TOP VIEW)**



**SN54ACT04 . . . FK PACKAGE  
(TOP VIEW)**



NC – No internal connection

## description/ordering information

The 'ACT04 devices contain six independent inverters. The devices perform the Boolean function  $Y = \bar{A}$ .

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74ACT04N	SN74ACT04N
	SOIC – D	Tube	SN74ACT04D	ACT04
		Tape and reel	SN74ACT04DR	
	SOP – NS	Tape and reel	SN74ACT04NSR	ACT04
	SSOP – DB	Tape and reel	SN74ACT04DBR	AD04
	TSSOP – PW	Tube	SN74ACT04PW	AD04
		Tape and reel	SN74ACT04PWR	
-55°C to 125°C	CDIP – J	Tube	SNJ54ACT04J	SNJ54ACT04J
	CFP – W	Tube	SNJ54ACT04W	SNJ54ACT04W
	LCCC – FK	Tube	SNJ54ACT04FK	SNJ54ACT04FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
H	L
L	H



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



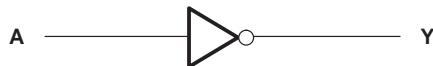
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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54ACT04, SN74ACT04 HEX INVERTERS

SCAS518C – JULY 1995 – REVISED OCTOBER 2003

## logic diagram, each inverter (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 200$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package .....	86°C/W
DB package .....	96°C/W
N package .....	80°C/W
NS package .....	76°C/W
PW package .....	113°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

## recommended operating conditions (see Note 3)

		SN54ACT04		SN74ACT04		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current		-24		-24	mA
$I_{OL}$	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		8		8	ns/V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54ACT04		SN74ACT04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 µA	4.5 V	4.4	4.49		4.4		4.4		V
		5.5 V	5.4	5.49		5.4		5.4		
	I <sub>OH</sub> = -24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I <sub>OH</sub> = -50 mA <sup>†</sup>	5.5 V				3.85				
	I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V						3.85		
V <sub>OL</sub>	I <sub>OL</sub> = 50 µA	4.5 V	0.001	0.1		0.1		0.1		V
		5.5 V	0.001	0.1		0.1		0.1		
	I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44		
		5.5 V		0.36		0.5		0.44		
	I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V				1.65				
	I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V						1.65		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V		±0.1		±1		±1		µA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		2		40		20		µA
ΔI <sub>CC</sub> <sup>‡</sup>	One input at 3.4 V, Other inputs at GND or V <sub>CC</sub>	5.5 V		0.6		1.6		1.5		mA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4.5						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

<sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

**switching characteristics over recommended operating free-air temperature range,  
V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			SN54ACT04		SN74ACT04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1	6	8.5	1	9	1	9	ns
t <sub>PHL</sub>			1	5.5	8	1	8.5	1	8.5	

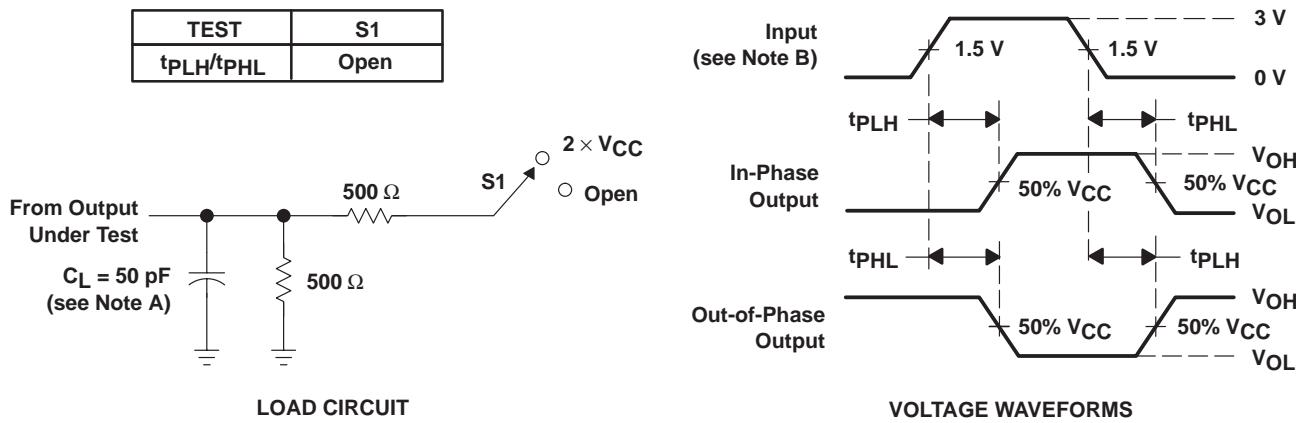
**operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C**

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	C <sub>L</sub> = 50 pF, f = 1 MHz	45	pF

# SN54ACT04, SN74ACT04 HEX INVERTERS

SCAS518C – JULY 1995 – REVISED OCTOBER 2003

## PARAMETER MEASUREMENT INFORMATION



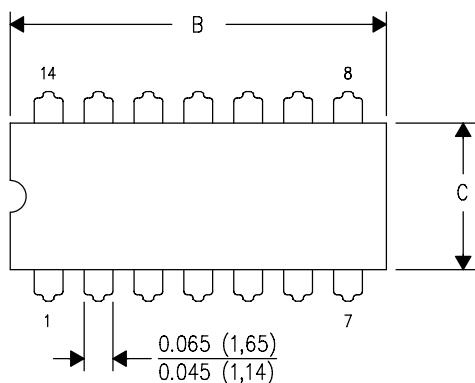
- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
  - C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

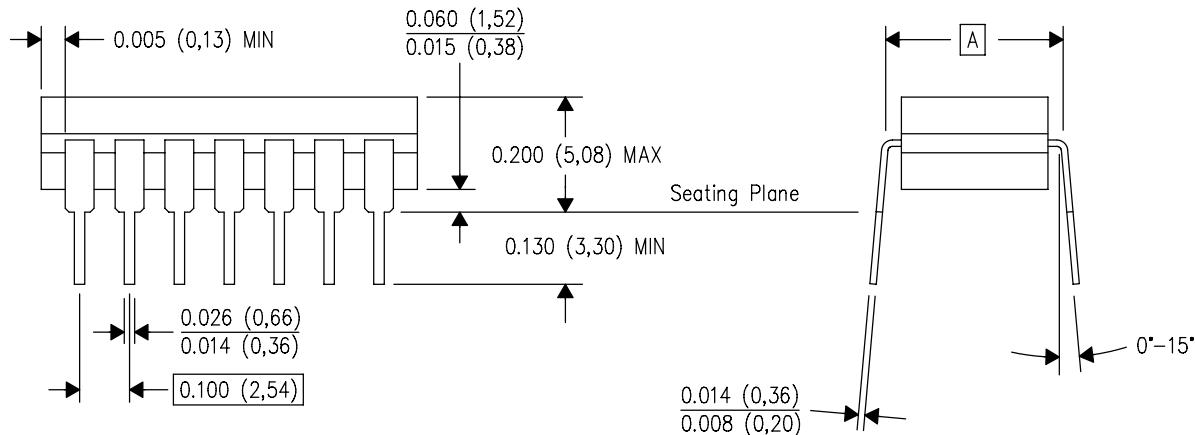
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS **\nDIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

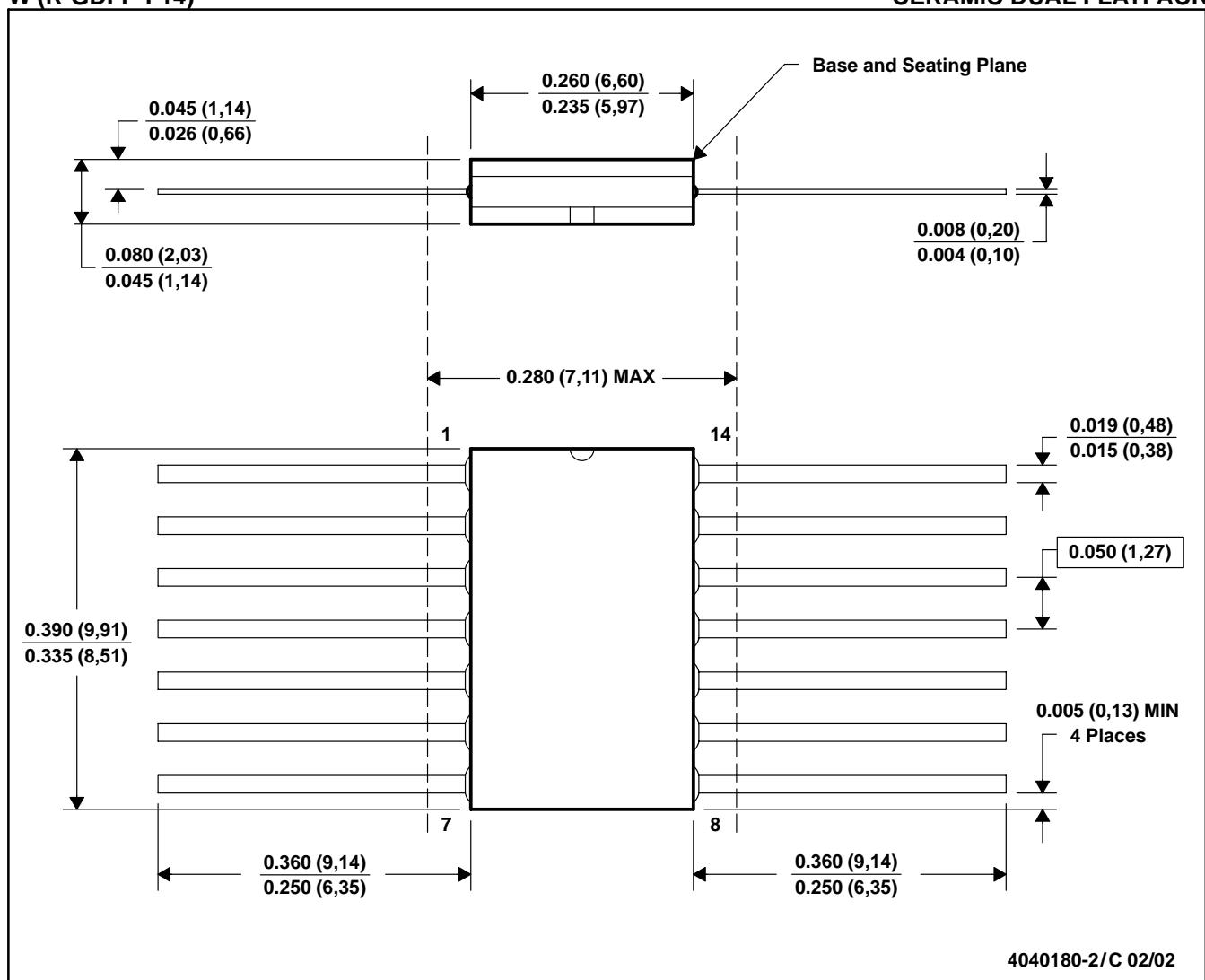


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

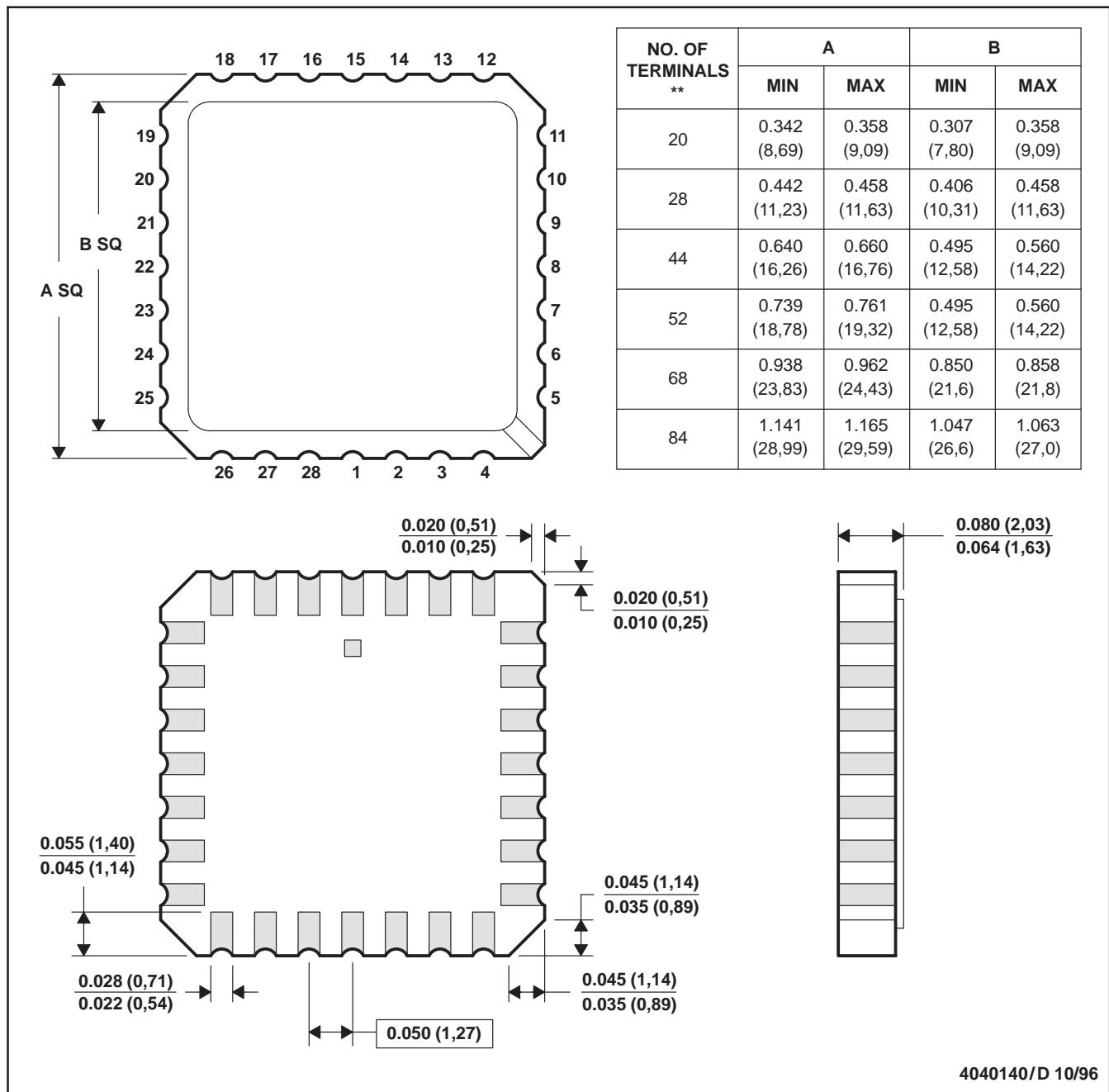


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only.  
 E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

E. Falls within JEDEC MS-004

4040140/D 10/96

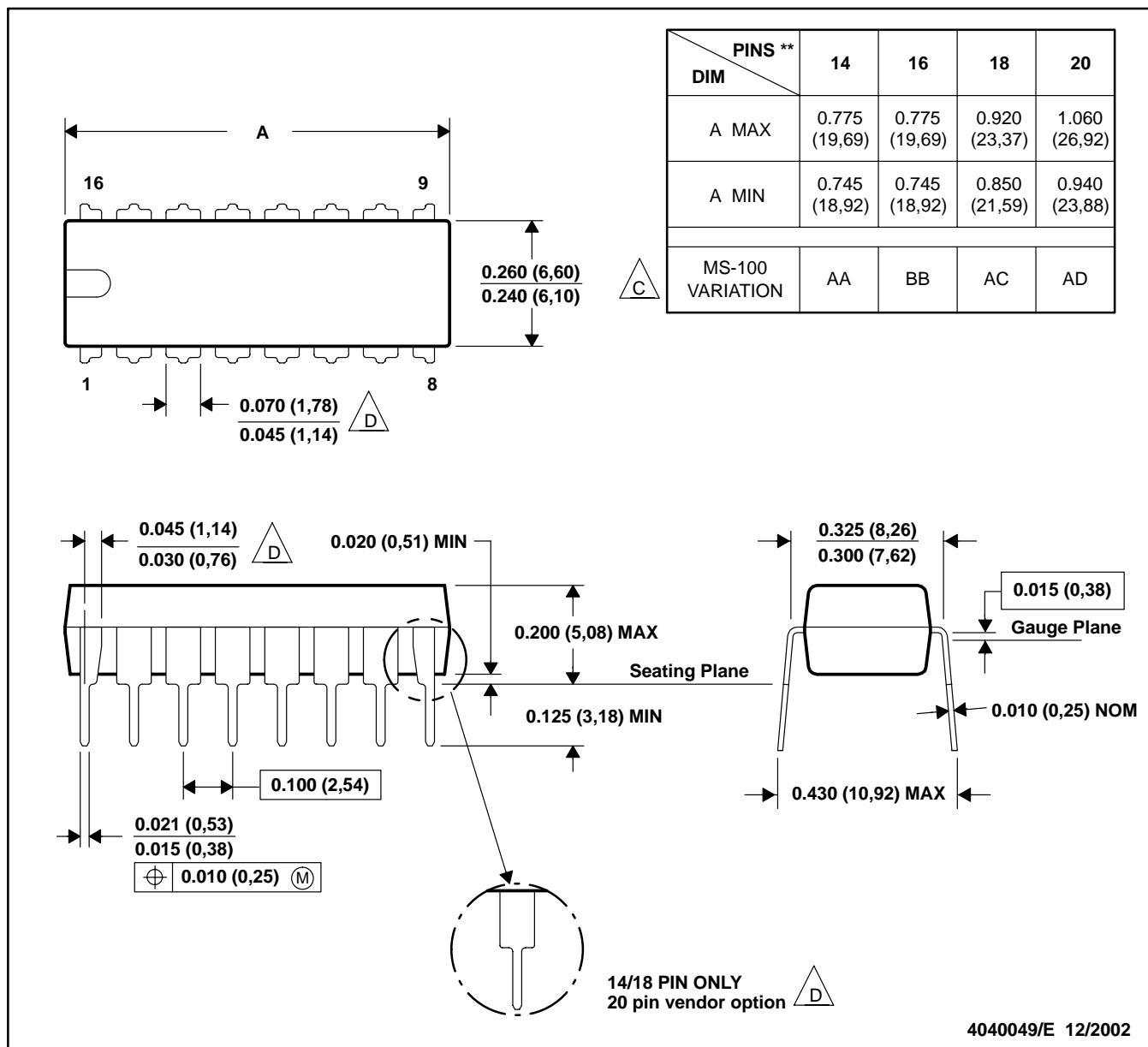
# MECHANICAL

MPDI002C – JANUARY 1995 – REVISED DECEMBER 20002

N (R-PDIP-T\*\*)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

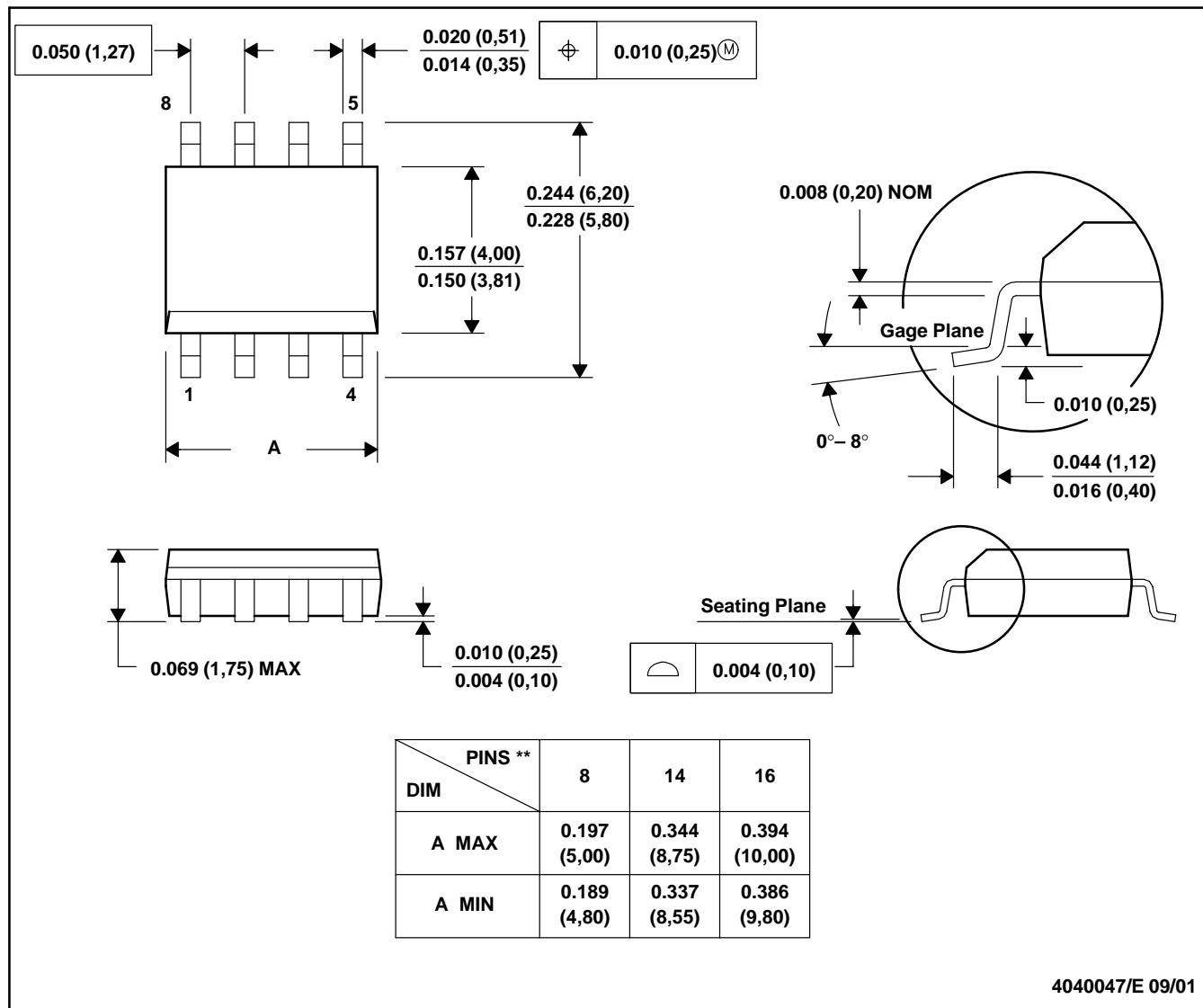
C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

## D (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



4040047/E 09/01

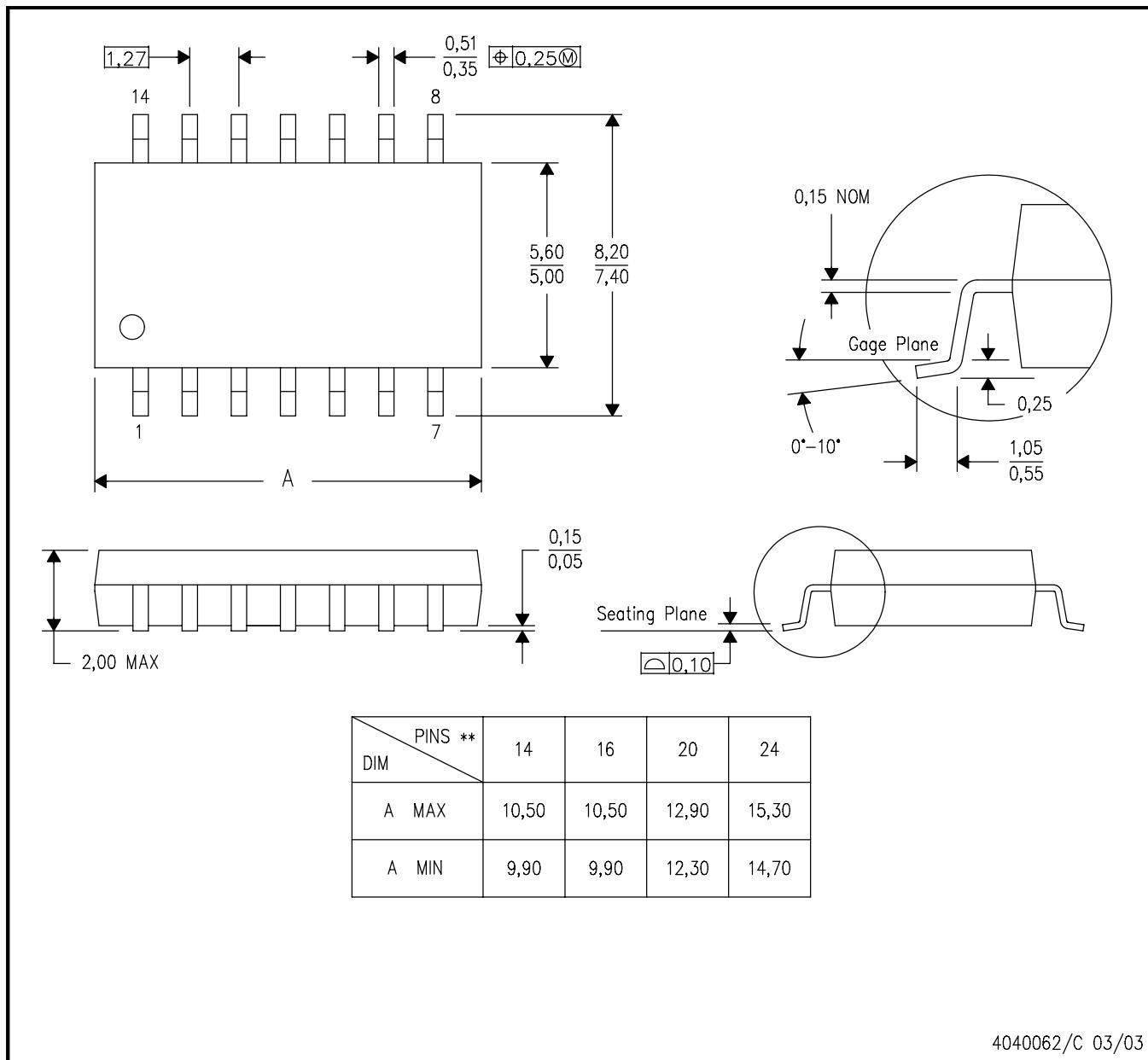
- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0.15).  
 D. Falls within JEDEC MS-012

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**14-PINS SHOWN**

**PLASTIC SMALL-OUTLINE PACKAGE**

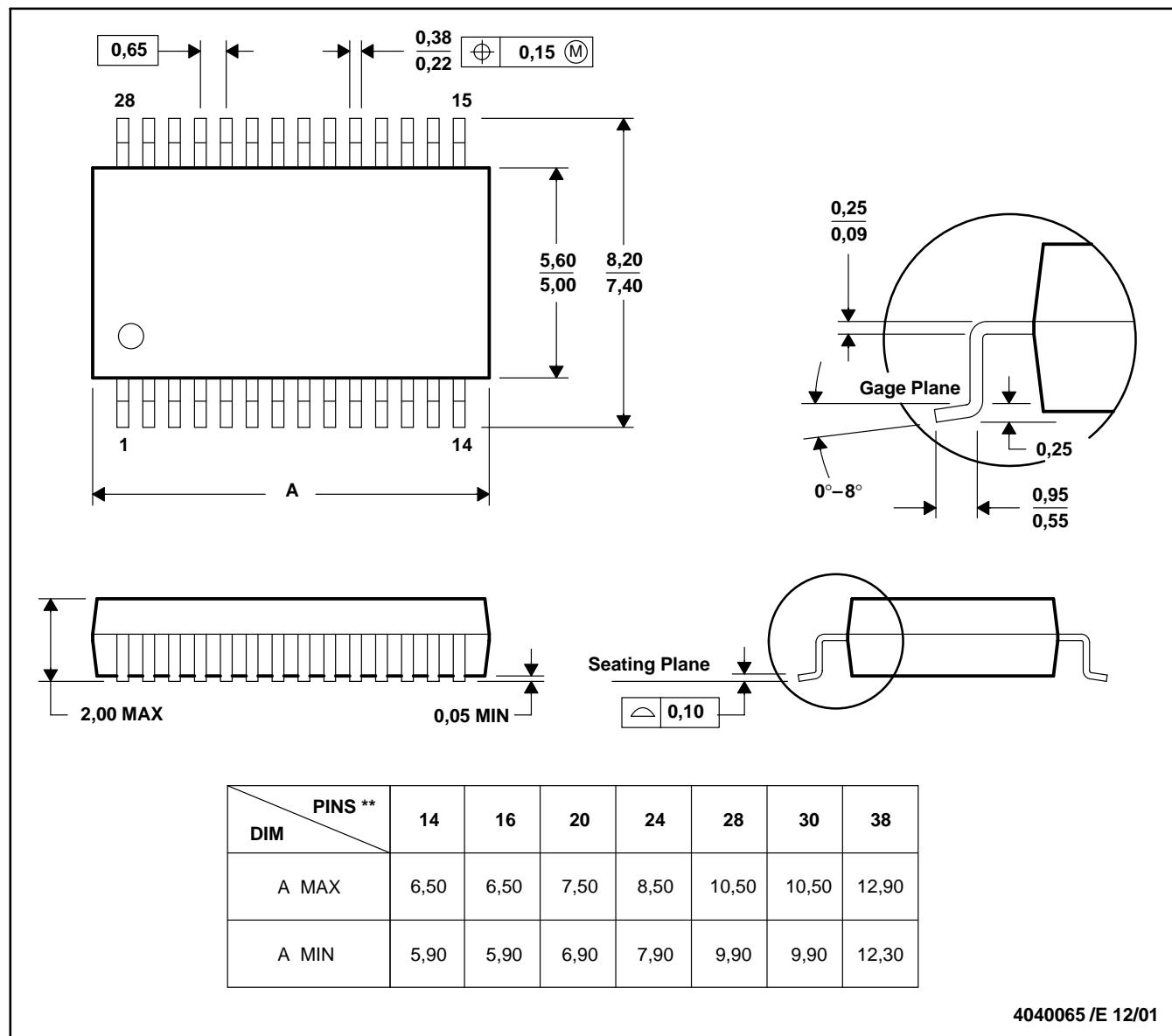


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN

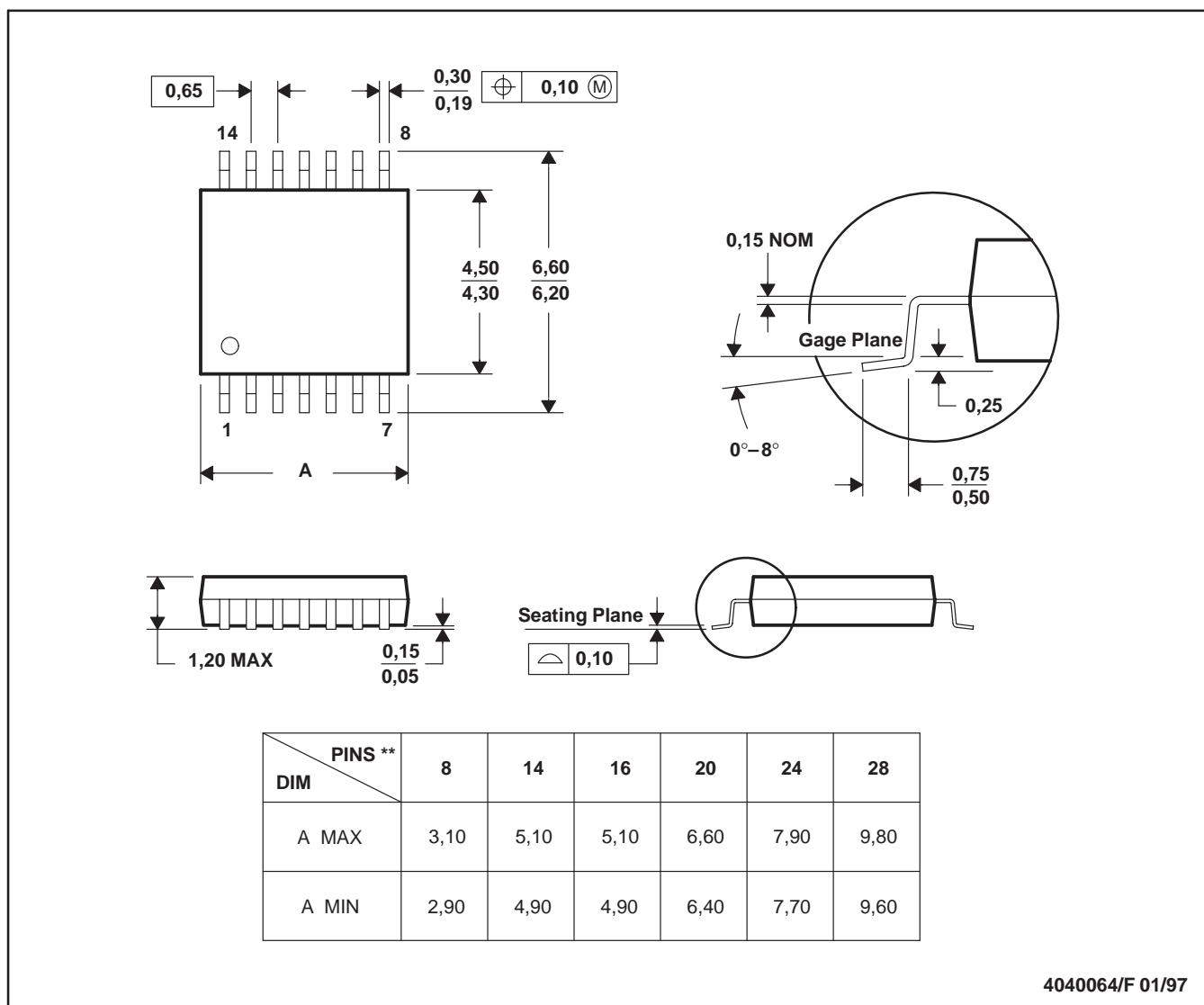


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
  - D. Falls within JEDEC MO-150

PW (R-PDSO-G<sup>\*\*</sup>)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
  - Falls within JEDEC MO-153

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